

SEMESTER 2 (SUMMER) EXAMINATIONS 1998-99

Applied Physics & Electronics, Experimental Physics, Physics & Computing – Paper 3

EP326: Solid State Physics

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Answer THREE questions

Time allowed: TWO hours

*Physical data for silicon at 300 K, and other constants**(a) Silicon at 300 K:*

N_c	=	$2.8 \times 10^{25} \text{ m}^{-3}$	N_v	=	$1.04 \times 10^{25} \text{ m}^{-3}$
μ_n	=	$0.14 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1}$	μ_p	=	$0.05 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1}$
D_n	=	$36 \times 10^{-4} \text{ m}^2 \text{ s}^{-1}$	D_p	=	$13 \times 10^{-4} \text{ m}^2 \text{ s}^{-1}$
n_i	=	$1.45 \times 10^{16} \text{ m}^{-3}$	E_G	=	1.12 eV

Relative dielectric constant, ϵ_s	=	11.9
Density of Si atoms (crystalline)	=	$5.0 \times 10^{28} \text{ atoms m}^{-3}$
Resistivity of intrinsic Si	=	$2300 \text{ } \Omega \text{ m}$

(b) Other constants:

kT	=	0.0259 eV at $T = 300\text{K}$
e	=	$1.602 \times 10^{-19} \text{ C}$
m_e	=	$9.11 \times 10^{-31} \text{ kg}$
h	=	$6.626 \times 10^{-34} \text{ J s}$
ϵ_0	=	$8.85 \times 10^{-12} \text{ F m}^{-1}$
Relative dielectric constant of SiO_2 , ϵ_{OX}	=	3.9

Q.1 Write full notes on any *two* of the following topics.

- (a) SPICE models and parameters for *either* the p-n diode *or* bipolar junction transistor.
- (b) The transport and continuity equations in semiconductors.
- (c) Switching speeds and minority charge storage in bipolar junction transistors.

Q.2 State the assumptions of the Feynman close coupling model for electrons in a 1-d crystal. The result of a Quantum Mechanical analysis using this model gives rise to the following energy band equation:

$$E(k) = E_0 - 2A \cos(ka)$$

Explain the physical significance of this equation, defining all the terms used in it. Show quantitatively how the equation predicts the existence of positive charge, positive mass, *holes* in semiconductors. Describe briefly how a general energy band theory for electrons accounts for the main qualitative features of conduction observed in metals, insulators, and semiconductors.

Q.3 Given (a) the Fermi-Dirac distribution equation: $F(E) = \frac{1}{\exp\left(\frac{E - E_F}{kT}\right) + 1}$, and,

(b) the formula for the density of available quantum states in the conduction band of a

semiconductor: $N(E) = \frac{4\pi}{h^3} (2m_e^*)^3 (E - E_C)^{0.5}$, show that the total number of free electrons n in a

semiconductor conduction band at temperature T , is given by: $n = N_C \exp\left(-\frac{(E_C - E_F)}{kT}\right)$. State

and carefully explain any assumptions made in your derivation. Say what N_C is, and give the algebraic expression for it.

Silicon is doped with phosphorous impurities at a concentration of 4×10^{22} atoms m^{-3} . Assuming 100% impurity ionisation, estimate the resultant shift in the Fermi energy, E_F , as measured from its intrinsic position, E_i .

Q.4 Give a labelled diagram, to help you to explain the fabrication and structure of a modern, high speed, drift, Bipolar Junction Transistor (BJT). How does the doping profile set up in the base help in improving the switching speed of such a device?

Define the *base transport factor*, b , and the *emitter injection efficiency*, γ , for a BJT. Equations for these two quantities are given below. Define all the terms used.

$$b = 1 - \frac{W^2}{2D_n\tau_n} \quad ; \quad \gamma = \left[1 + \frac{WN_A L_n}{L_E N_D L_p} \right]^{-1}$$

A particular npn BJT has a base width of $0.8 \mu m$, and the minority carrier lifetime in the base is 800 ns. If the emitter injection efficiency $\gamma = 0.9975$, calculate the values of the common base and common emitter current gains, α and β , for the device.

Q.5 Identify the following MOSFET equation, defining all the terms used in it, and explaining their physical origin.

$$V_{TH} = \phi_{MS} - \frac{Q_{OX}}{C_{OX}} - \frac{Q_{BO}}{C_{OX}} + 2\phi_F$$

A NMOSFET transistor is fabricated with a gate oxide thickness $t_{OX} = 60$ nm on a p type silicon substrate with doping level $N_A = 9 \times 10^{21} m^{-3}$. The device parameters are measured or calculated as: $\phi_{MS} = -0.95$ V, $\phi_s(inv) = 0.71$ V, maximum depletion depth $W_M = 0.33 \mu m$, $V_{TH} = 0.35$ V. Calculate the gate capacitance C_{OX} , the maximum semiconductor depletion charge density Q_D , and the density of surface states N_{OX} at the oxide-semiconductor interface.

Estimate (quantitatively) the ion implant dose required to raise the threshold voltage of this device to 1.5 V. What element would be used for the implant?